

**INFORMATION DISCLOSURE CITATION**  
(Use several sheets if necessary)

Docket Number (Optional)

**BUR920040182US1**

Application Number

**10/711,418**

Applicant(s)

**Fen Chen et al.**

Filing Date

**09/17/2004**

Group Art Unit

**2825**

**U.S. PATENT DOCUMENTS**

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

**U.S. PATENT APPLICATION PUBLICATIONS**

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

**FOREIGN PATENT DOCUMENTS**

	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
							YES	NO
SW		EP 1 576 680 A1	02.01.2004	European Patent Office				✓

**OTHER DOCUMENTS**

(Including Author, Title, Date, Pertinent Pages, Etc.)

SW		USING THE TEMPERATURE COEFFICIENT OF THE RESISTANCE (TCR) AS EARLY RELIABILITY INDICATOR FOR STRESSVOIDING RISKS IN CU INTERCONNECTS, by A. von Glasow et al., Copyright 2003, pp. 126-131.

EXAMINER

/Stacy Whitmore/

DATE CONSIDERED

10/16/2006

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

IDS - 09/17/2004 **ELECTRONIC INFORMATION DISCLOSURE STATEMENT**

Electronic Version v18

Stylesheet Version v18.0

**Title of  
Invention****NON-DESTRUCTIVE EVALUATION OF MICROSTRUCTURE  
AND INTERFACE ROUGHNESS OF ELECTRICALLY  
CONDUCTING LINES IN SEMICONDUCTOR INTEGRATED  
CIRCUITS IN DEEP SUB-MICRON REGIME**

Application Number :

Confirmation Number:

First Named Applicant: Fen Chen

Attorney Docket Number: BUR920040182US1

Art Unit: 2825

Examiner: S. Whitmore

Search string: ( 6603321 or 20010046276 ).pn

**US Patent Documents****Note: Applicant is not required to submit a paper copy of cited US Patent Documents**

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
SW	1	6603321	2003-08-05	Filippi, Jr. et al			

**US Published Applications****Note: Applicant is not required to submit a paper copy of cited US Published Applications**

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
SW	1	20010046276	2001-11-29	Schneider et al			

**Signature**

Examiner Name	Date
/Stacy Whitmore/	10/16/2006